

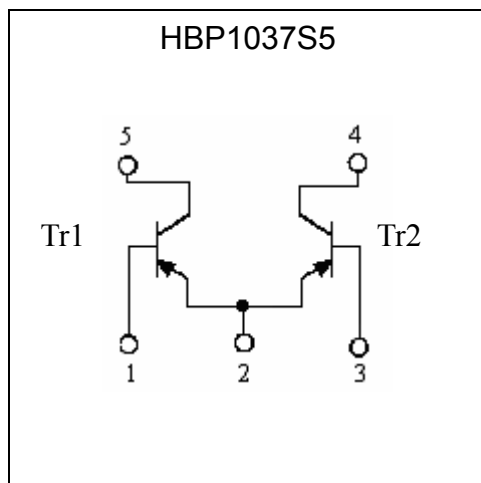
**General Purpose PNP Epitaxial Planar Transistors  
 (dual transistors)**

# HBP1037S5

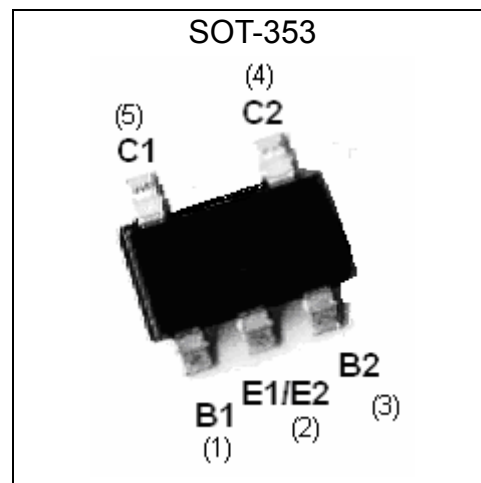
**Features**

- Two BTA1037 chips in a SOT-353 package.
- Mounting possible with SOT-323 automatic mounting machines.
- Mounting cost and area can be cut in half.
- Excellent hFE linearity
- Pb-free lead plating and halogen free package.

**Equivalent Circuit**



**Outline**



**The following characteristics apply to both Tr1 and Tr2**

**Absolute Maximum Ratings** (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V <sub>CB0</sub>	-60	V
Collector-Emitter Voltage	V <sub>CE0</sub>	-50	V
Emitter-Base Voltage	V <sub>EB0</sub>	-6	V
Collector Current	I <sub>C</sub>	-150	mA
Base Current	I <sub>B</sub>	-30	mA
Power Dissipation	P <sub>D</sub>	200(total) *1	mW
Junction Temperature	T <sub>j</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-55~+150	°C

Note : \*1 150mW per element must not be exceeded

**Characteristics (Ta=25°C)**

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-60	-	-	V	IC=-50μA
BVCEO	-50	-	-	V	IC=-1mA
BVEBO	-6	-	-	V	IE=-50μA
ICBO	-	-	-0.1	μA	VCB=-60V
IEBO	-	-	-0.1	μA	VEB=-6V
*VCE(sat)	-	-0.2	-0.3	V	IC=-100mA, IB=-10mA
*hFE	200	-	400		VCE=-6V, IC=-1mA
fT	80	110	-	MHz	VCE=-12V, IC=-1mA, f=100MHz
Cob	-	2.3	3.5	pF	VCB=-10V, f=1MHz

\*Pulse Test: Pulse Width ≤380μs, Duty Cycle≤2%

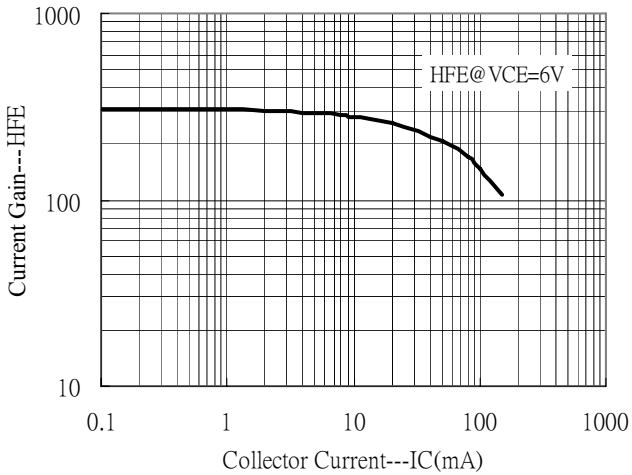
**Ordering Information**

Device	Package	Shipping	Marking
HBP1037S5	SOT-353 (Pb-free lead plating and halogen free package)	3000 pcs / Tape & Reel	SGR

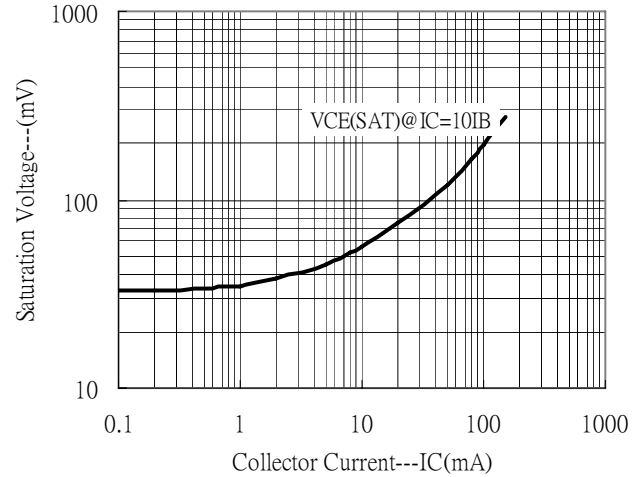


### Typical Characteristics

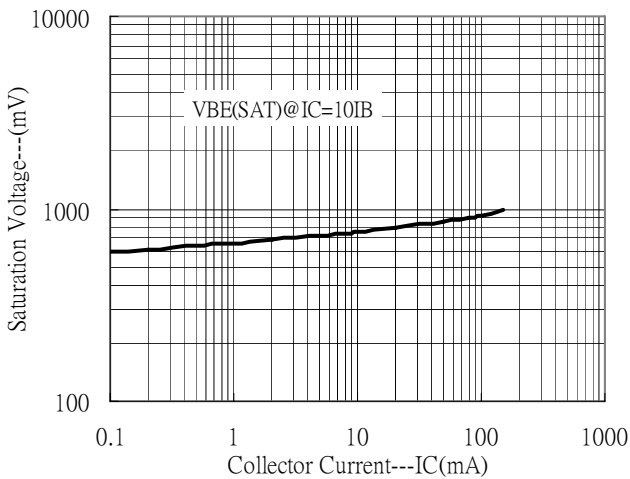
Current Gain vs Collector Current



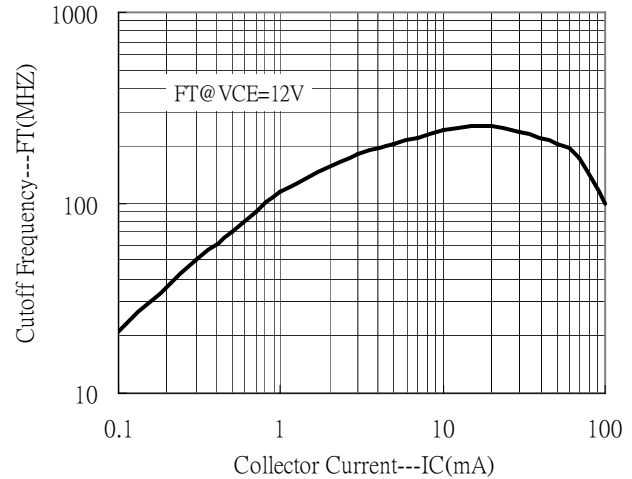
Saturation Voltage vs Collector Current



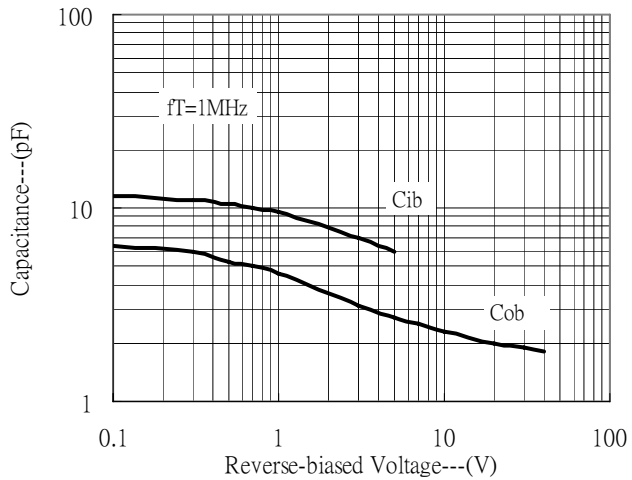
Saturation Voltage vs Collector Current



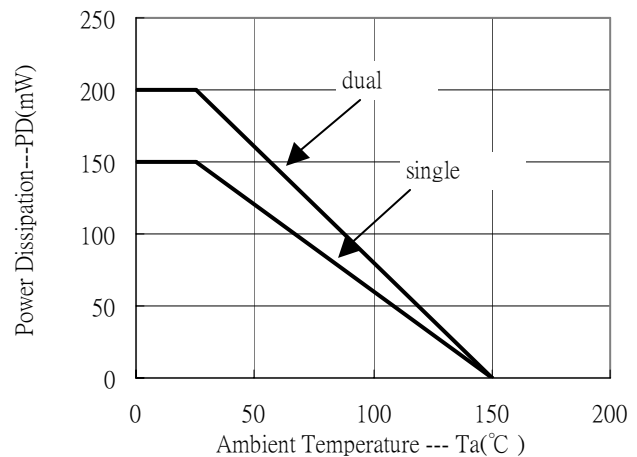
Cutoff Frequency vs Collector Current



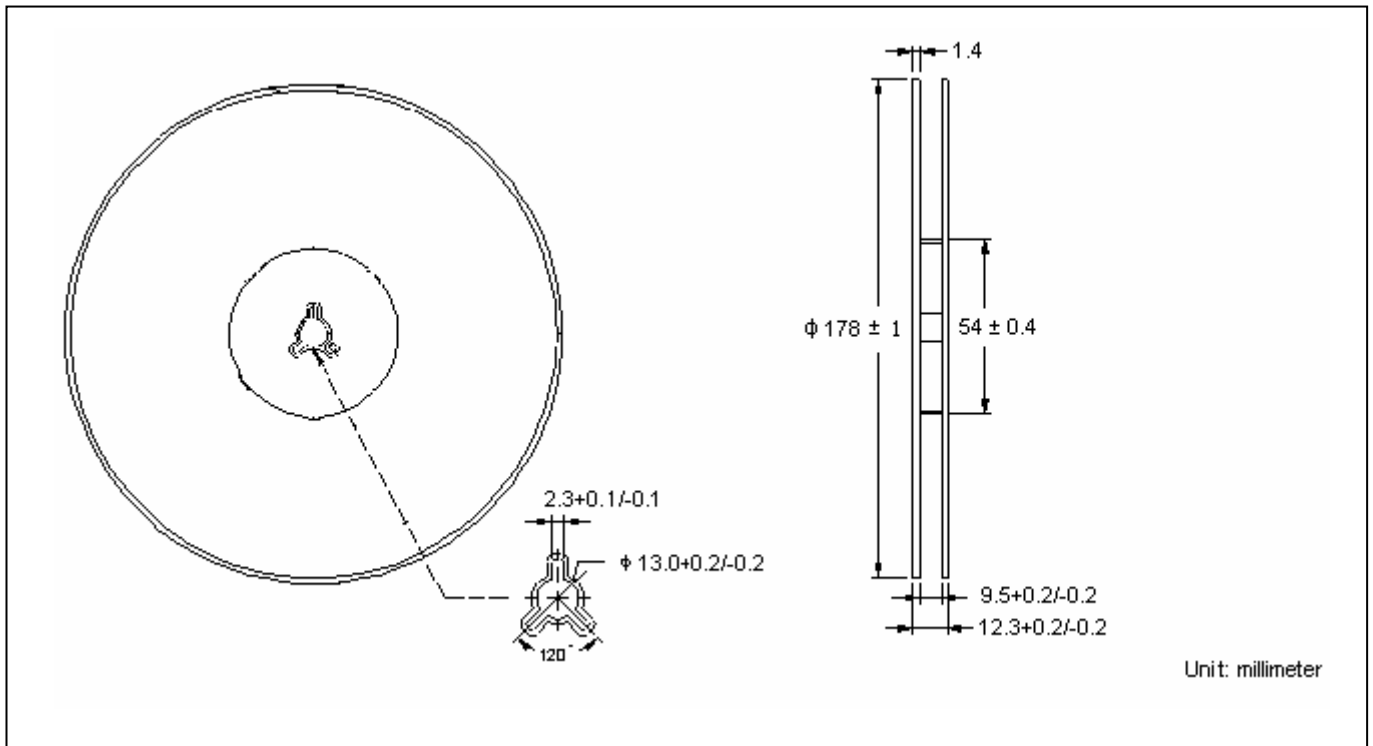
Capacitance Characteristics



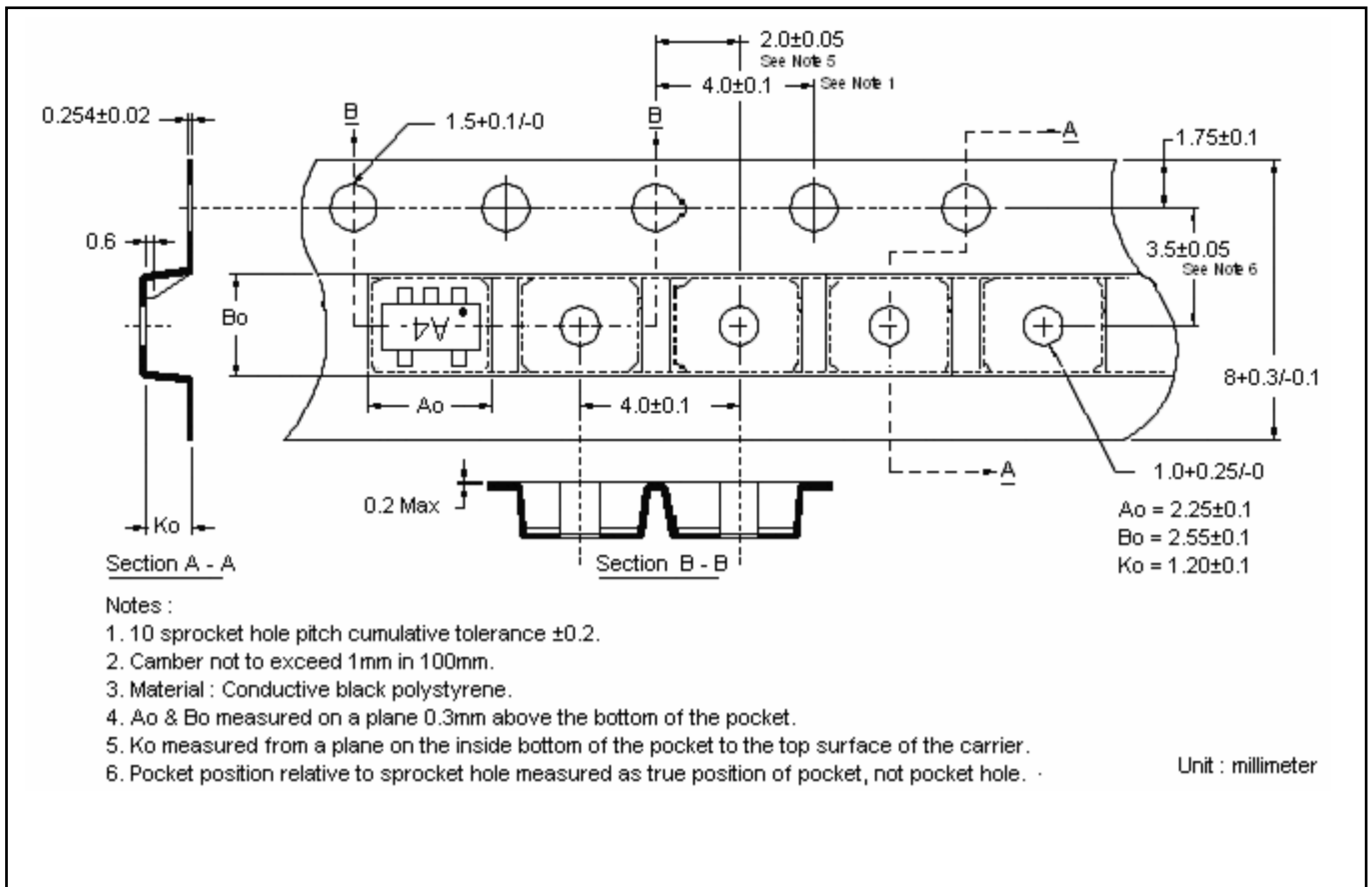
Power Derating Curves



**Reel Dimension**



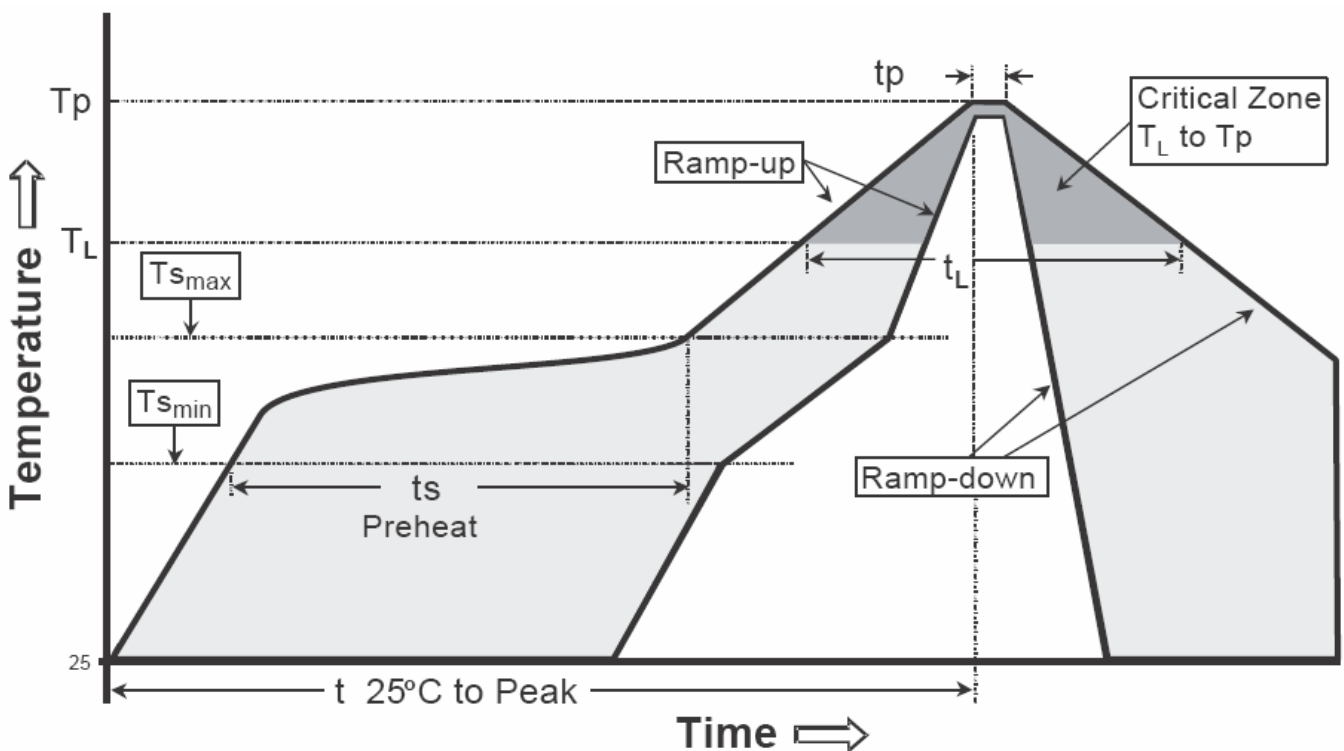
**Carrier Tape Dimension**



**Recommended wave soldering condition**

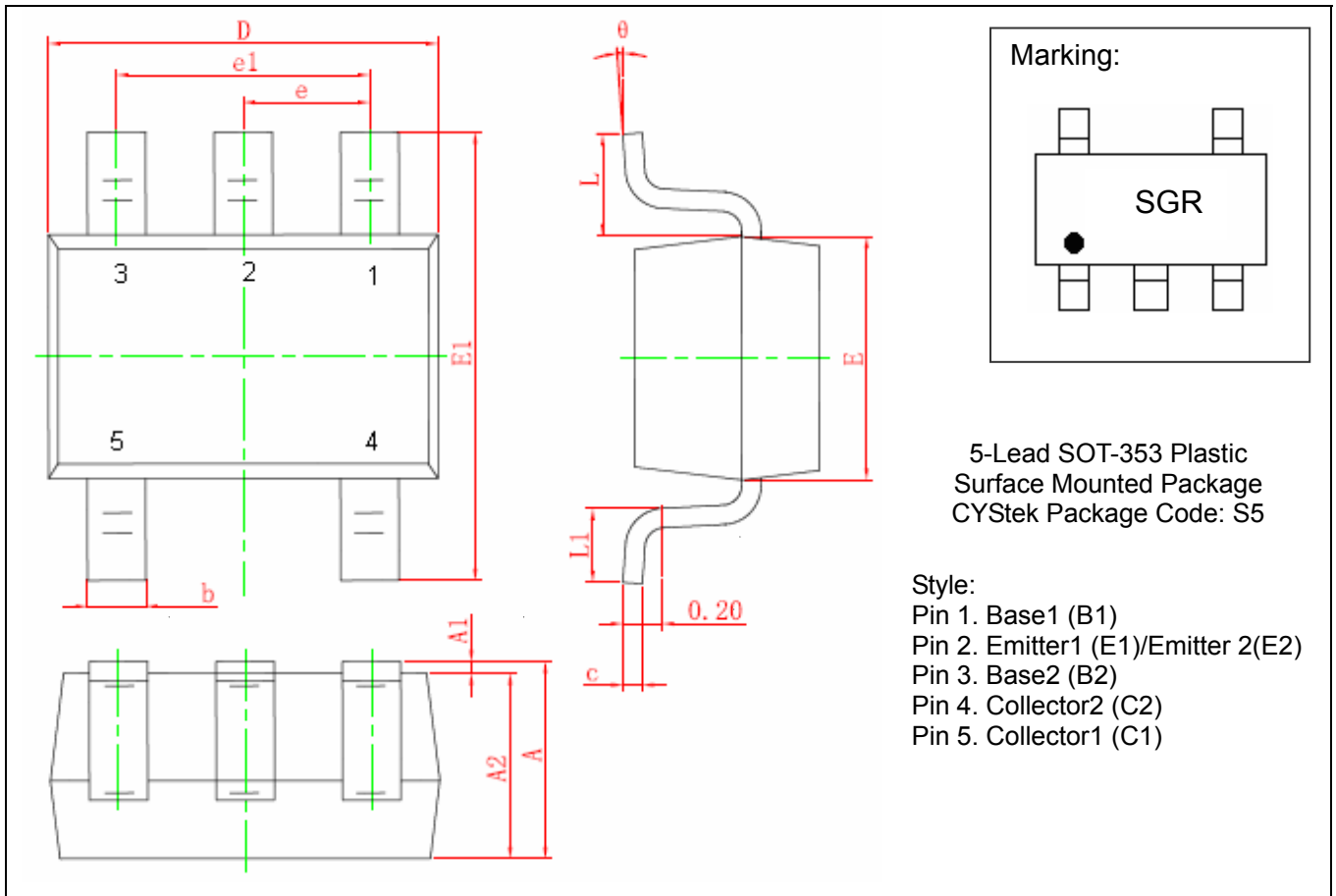
Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

**Recommended temperature profile for IR reflow**



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T <sub>smax</sub> to T <sub>p</sub> )	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T <sub>s min</sub> )	100°C	150°C
-Temperature Max(T <sub>s max</sub> )	150°C	200°C
-Time(t <sub>s min</sub> to t <sub>s max</sub> )	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T <sub>L</sub> )	183°C	217°C
- Time (t <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak Temperature(T <sub>P</sub> )	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

**SOT-353 Dimension**



\*:Typical

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043	E1	2.150	2.450	0.085	0.096
A1	0.000	0.100	0.000	0.004	e	0.650*		0.026*	
A2	0.900	1.000	0.035	0.039	e1	1.200	1.400	0.047	0.055
b	0.150	0.350	0.006	0.014	L	0.525	REF	0.021	REF
c	0.080	0.150	0.003	0.006	L1	0.260	0.460	0.010	0.018
D	2.000	2.200	0.079	0.087	θ	0°	8°	0°	8°
E	1.150	1.350	0.045	0.053					

Notes : 1.Controlling dimension : millimeters.  
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

**Material :**

- Lead : Pure tin plated.
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0.

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